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(21) International Application Number: PCT/US96/18206 (22) International Filing Date: 13 November 1996 (13.11.96) (30) Priority Data: 08/565,539 30 November 1995 (30.11.95) US (71) Applicant: THE WHITAKER CORPORATION [US/US]; Suite 450, 4550 New Linden Hill Road, Wilmington, DE 19808 (US). (72) Inventor: TAYLOR, Attalee, S.; R.D. #1 Box 429G, Palmyra, PA 17078 (US). (74) Agents: KAPALKA, Robert, J. et al.; The Whitaker Corporation, Suite 450, 4550 New Linden Hill Road, Wilmington, DE 19808 (US).			(81) Designated States: CN, JP, KR, SG, European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published With international search report.

(54) Title: SURFACE MOUNT SOCKET FOR AN ELECTRONIC PACKAGE AND CONTACT FOR USE THEREWITH

(57) Abstract

A socket (6) for an electronic package (2) comprises a dielectric housing (10) having contacts (20) each with a surface mount section (50) extending below a bottom surface (14) of the housing for engagement with a respective circuit trace on a circuit board. The surface mount section (50) of each contact has a convex bottom surface (52) with a shape which simulates at least a lower surface portion of a solder ball, whereby the socket imitates the footprint of a ball grid array package.

